

5-147383-3 ✓ ACTIVE

AMPMODU | AMPMODU 50/50 Grid

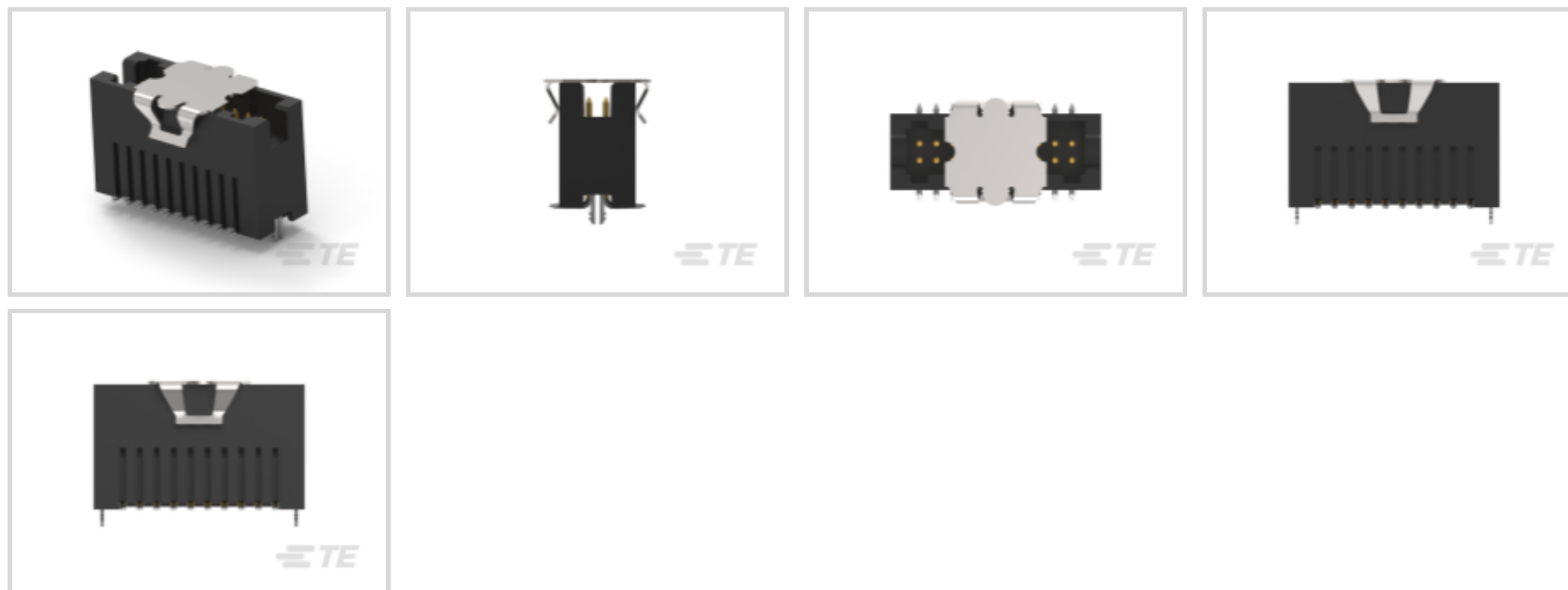
TE Internal #: 5-147383-3

PCB Mount Header, Vertical, Board-to-Board, 30 Position, 1.27 mm
[.05 in] Centerline, Fully Shrouded, Gold, Surface Mount, Black,
AMPMODU 50/50 Grid

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Connectors > PCB Connectors > PCB Headers & Receptacles



EU RoHS Compliance: **Compliant**

EU ELV Compliance: **Compliant**

PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Features

Termination Features

	.03 in
Termination Post & Tail Diameter	.46 mm[.018 in]
Termination Method to PCB	Surface Mount

Contact Features

	150 μ m
Contact Underplating Material	Nickel
Mating Pin Diameter	.46 mm[.018 in]
Contact Shape & Form	Round
Contact Base Material	Phosphor Bronze
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	.5 A

Other



EU RoHS Compliance	Compliant
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EU ELV Compliance	Compliant
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Product Type Features

PCB Connector Assembly Type	PCB Mount Header
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Connector System	Board-to-Board
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Header Type	Fully Shrouded
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Sealable	No
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Connector & Contact Terminates To	Printed Circuit Board
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Configuration Features

Connector Contact Load Condition	Selectively Loaded
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Board-to-Board Configuration	Parallel
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PCB Mount Orientation	Vertical
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Number of Positions	30
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Number of Rows	2
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Electrical Characteristics

Operating Voltage	30 VAC
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Body Features

PCB Retention Feature Material	Copper Alloy
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PCB Retention Feature Plating Material	Tin over Nickel
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Primary Product Color	Black
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Mechanical Attachment

Mating Alignment Type	Keyed
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PCB Mount Retention Type	Hold-Down Post
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PCB Mount Retention	With
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Mating Alignment	With
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Housing Features

Housing Material	LCP (Liquid Crystal Polymer)
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Centerline (Pitch)	1.27 mm [.05 in]
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Dimensions

Row-to-Row Spacing	1.27 mm [.05 in]
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Stack Height	9.91 mm [.39 in]
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Usage Conditions



Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
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Operation/Application

Assembly Process Feature	Vacuum Cover
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Industry Standards

Compatible With Approved Standards Products	UL E28476, CSA LR7189
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	400
Packaging Method	Tape & Reel

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

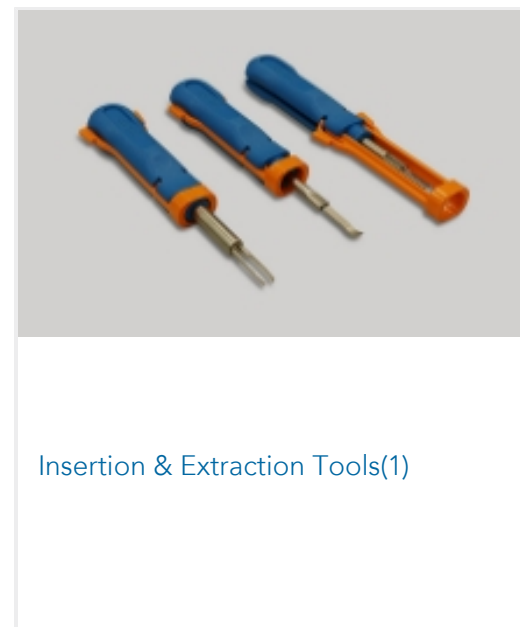
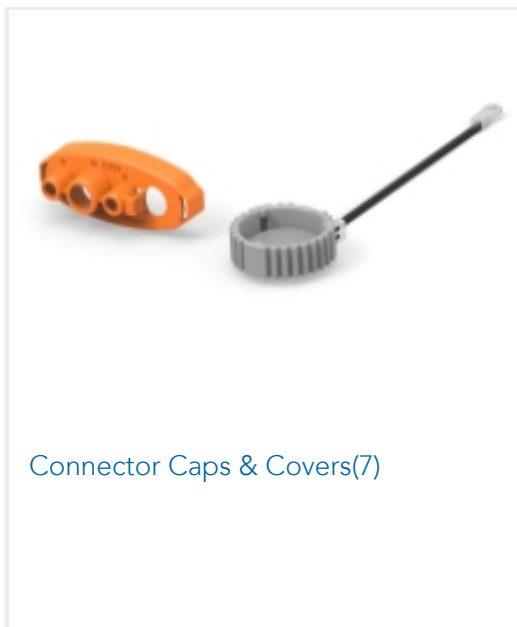
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | AMPMODU 50/50 Grid



Customers Also Bought

Documents

Product Drawings

[30 50/50 HDR SMT.390 W/HD VC](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_5-147383-3_D.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_5-147383-3_D.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_5-147383-3_D.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION1AND2](#)

English

[Ribbon Cable Interconnect Solutions](#)



English

[Fine Pitch Stacking Connectors - 1.27mm AMPMODU 50/50 Grid Connectors](#)

English

[Product Specifications](#)

[Product Specification](#)

English

[Agency Approvals](#)

[UL Report](#)

English